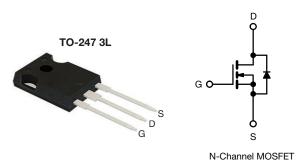


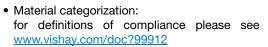
MaxSiC™ 1200 V N-Channel SiC MOSFET



Marking Code: 120A250FW

FEATURES

- · Fast switching speed
- Short circuit withstand time 3 µs





APPLICATIONS

- Charger
- Industrial UPS
- Boost inverter
- DC/DC converter

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	1200			
R _{DS(on)} typ. (mΩ) at 25 °C	V _{GS} = 20 V 250			
Q _g typ. (nC)	20			
I _D (A)	10.5			
C _{oss} (pF)	21.2			
P _D (W)	56			
Configuration	Single			

ORDERING INFORMATION	
Package	TO-247 3L
Lead (Pb)-free and halogen-free	MXP120A250FW-Y-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °	C, unless otherwis	se noted)		
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage ^a		V_{DS}	1200	V
Gate-source voltage		V_{GS}	-10 / +22]
Continuous drain current	T _C = 25 °C	I _D	10.5	
	T _C = 100 °C	I _D	6.7	Α
Pulsed drain current b		I _{DM}	21	
Short-circuit withstand time		T _{SC}	3	μs
Maximum power dissipation	T _C = 25 °C	P_{D}	56	14/
	T _C = 100 °C	P_{D}	22	W
Operating junction and storage temperature range		T _J , T _{sta}	-55 to +150	°C

Notes

- a. $T_J = 25$ °C to 150 °C
- b. Repetitive rating; pulse width limited by maximum junction temperature

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	-	40	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	2.24	G/ VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$		1200	-	-	V
Cata actives threshold valtage (N)	V	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 10 \text{ mA}$		3.1	-	V
Gate-source threshold voltage (N)	V _{GS(th)}	$V_{DS} = V_{GS}$	I _D = 10 mA, T _J = 150 °C	-	2.3	-	V
Gate-source leakage	lasa	V _{GS} =	$V_{GS} = +22 \text{ V}, V_{DS} = 0 \text{ V}$ $V_{GS} = -10 \text{ V}, V_{DS} = 0 \text{ V}$		-	100	- nA
Gate-Source leakage	I _{GSS}	V _{GS} =			-	-100	
Zero gate voltage drain current	I _{DSS}	V _{DS} =	960 V, V _{GS} = 0 V	-	-	10	μΑ
		V _{GS}	= 20 V, I _D = 4 A	-	250	313	
Drain-source on-state resistance		V _{GS} = 20 \	/, I _D = 4 A, T _J = 150 °C	-	380	475	mΩ
Drain-source on-state resistance	R _{DS(on)}	V _{GS}	= 18 V, I _D = 4 A	-	287	359	
		V _{GS} = 18 \	V _{GS} = 18 V, I _D = 4 A, T _J = 150 °C		395	494	
Dynamic							
Input capacitance	C _{iss}		$V_{GS} = 0 \text{ V},$ $V_{DS} = 800 \text{ V},$ f = 1 MHz		447	-	pF
Output capacitance	C _{oss}] ,			21.2	-	
Reverse transfer capacitance	C _{rss}				3.2	-	
Total gate charge	Qg				20.3	-	
Gate-source charge	Q_{gs}	V _{GS} = 18 V	$V_{GS} = 18 \text{ V}$ $I_D = 4 \text{ A}, V_{DS} = 800 \text{ V}$	-	5.5	-	nC
Gate-drain charge	Q_{gd}			-	7.9	-	
Gate Resistance	R_g	V _{DS}	V _{DS} = 0 V, f = 1 MHz		34	-	Ω
Switching Characteristics							
Turn-on delay time	t _{d(on)}		$V_{GS} = -5 \text{ V} \sim 18 \text{ V}, I_D = 4 \text{ A},$		10	-	
Rise time	t _r				11.5	-	ns
Turn-off delay time	t _{d(off)}	V _{GS} = -			9.5	-	
Fall time	t _f	$V_{DS} = 800 \text{ V}, R_{g(ext)} = 4.4 \Omega$		-	15	-	
Turn-on switching energy	E _{on}			-	76	-	
Turn-off switching energy	E _{off}			-	5	-	μJ
Reverse Diode Characteristics							
Reverse recovery time	t _{rr}	Vge	$V_{GS} = -5 \text{ V}, I_{SD} = 4 \text{ A},$		7.5	-	ns
Reverse recovery charge	Q _{rr}	$V_{R} = 800 \text{ V}$ $V_{R} = 800 \text{ V}$ $V_{R} = 1000 \text{ A/µs}$		-	12	-	nC
Reverse recovery current	I _{rrm}			-	2.8	-	Α

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

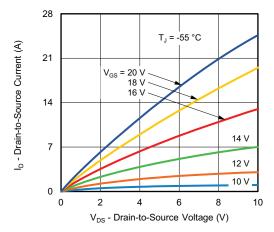


Fig. 1 - Typical Output Characteristics

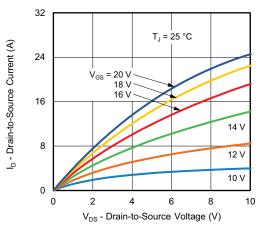


Fig. 2 - Typical Output Characteristics

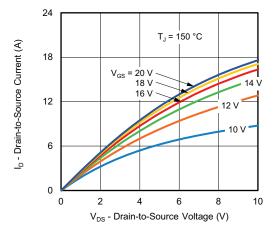


Fig. 3 - Typical Output Characteristics

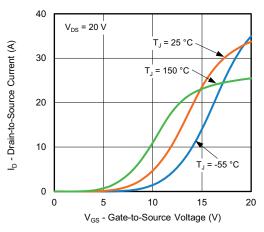


Fig. 4 - Typical Transfer Characteristics

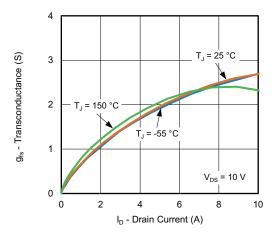


Fig. 5 - Forward Transconductance vs. Drain Current

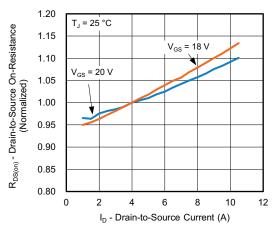


Fig. 6 - Normalized On-Resistance vs. Drain-to-Source Current

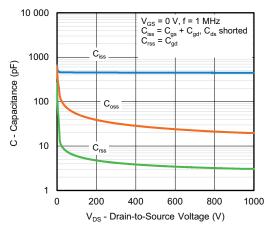


Fig. 7 - Typical Capacitance vs. Drain-to-Source Voltage

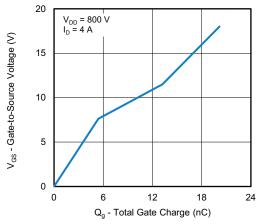


Fig. 8 - Typical Gate Charge vs. Gate-to-Source Voltage

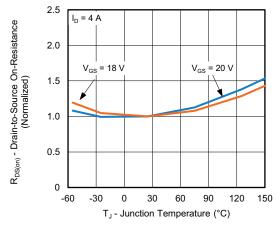


Fig. 9 - Normalized On-Resistance vs. Temperature

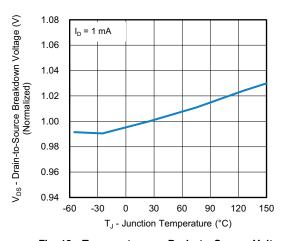


Fig. 10 - Temperature vs. Drain-to-Source Voltage

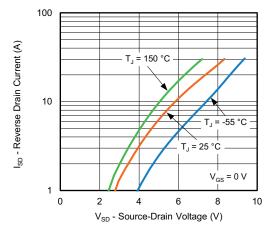


Fig. 11 - Typical Source-Drain Diode Forward Voltage

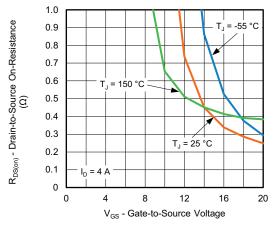


Fig. 12 - On-Resistance vs. Gate-to-Source Voltage

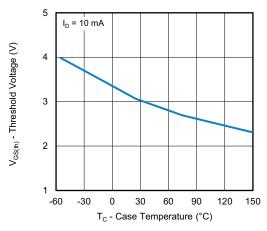


Fig. 13 - Threshold Voltage vs. Case Temperature

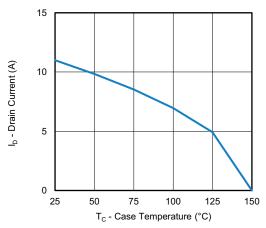


Fig. 14 - Drain Current vs. Case Temperature

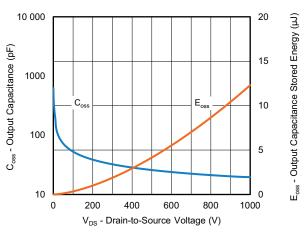


Fig. 15 - Output Capacitance and its Stored Energy vs. Drain-to-Source Voltage

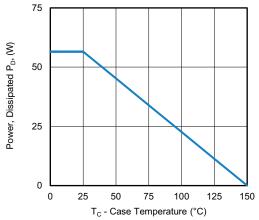


Fig. 16 - Power, Dissipated P_D vs. Case Temperature

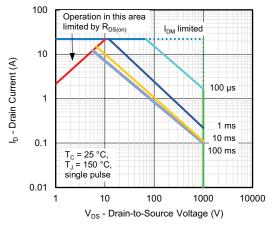


Fig. 17 - Safe Operating Area

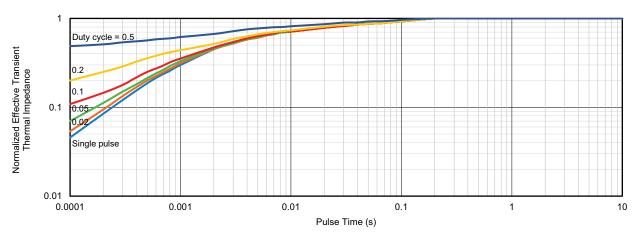


Fig. 18 - Normalized Effective Transient Thermal Impedance



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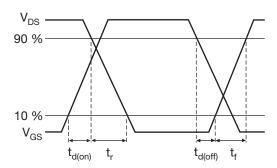


Fig. 19 - Waveforms of Switching Time

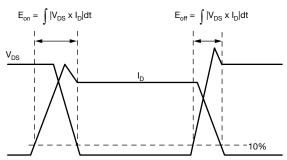


Fig. 20 - Waveforms for Switching Energy

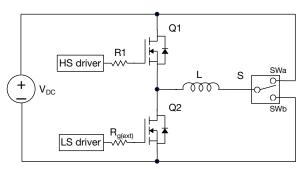


Fig. 21 - Switching and Reverse Diode Characteristics Measurement Circuit

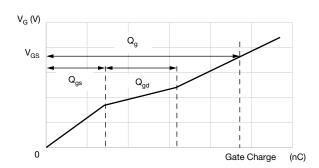


Fig. 22 - Waveforms for Gate Charge

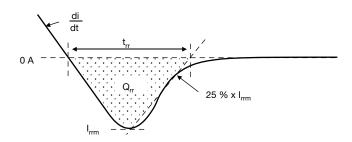


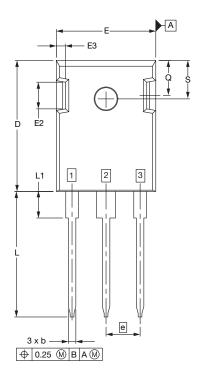
Fig. 23 - Waveforms for Reverse Recovery

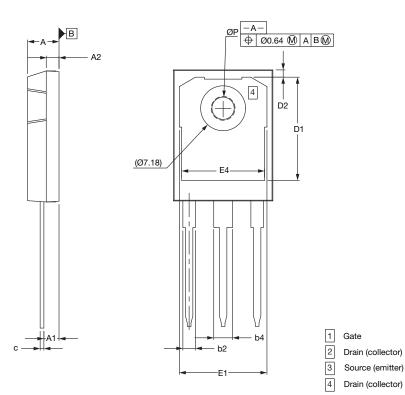
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Case Outline for TO-247AD 3L

FACILITY CODE: N





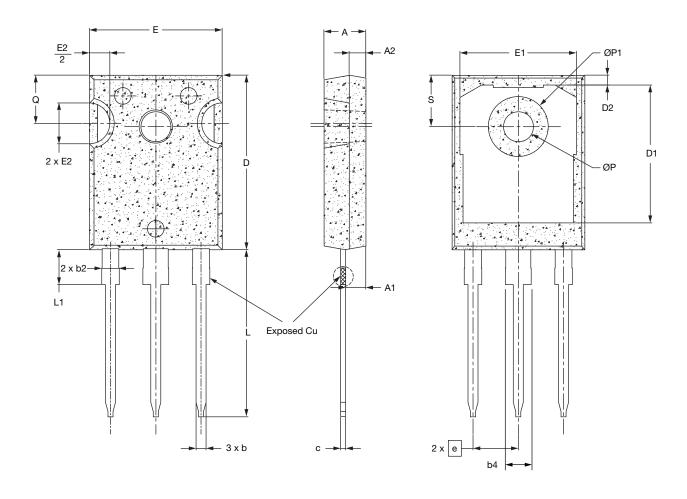
DIM.	MILLIMETERS		
DIIVI.	MIN.	MAX.	
A	4.83	5.21	
A1	2.29	2.54	
A2	1.91	2.16	
b	1.07	1.33	
b2	1.91	2.41	
b4	2.87	3.38	
С	0.55	0.68	
D	20.80	21.10	
D1	16.25	17.65	
D2	0.95	1.25	
Е	15.75	16.13	
E1	13.10	14.15	
E2	3.68	5.10	
E3	1.00	1.90	
E4	12.38	13.43	
е	5.44	BSC.	
N	3	3	
L	19.81	20.32	
L1	4.10	4.40	
ØP	3.51	3.65	
Q	5.49	6.00	
S	6.04	6.30	

Notes

- All metal surfaces: tin plated (MATTE), except area of cut Dimensioning and toleranceing confirm to ASME Y14.5M-1994
- All dimensions are in millimeters
- This drawing will meet all dimensions requirement of JEDEC outlines TO-247 AD



FACILITY CODE: 9







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DIM	MILLIMETERS				
DIM.	MIN.	NOM.	MAX.		
Α	4.83	5.02	5.21		
A1	2.29	2.41	2.55		
A2	1.50	2.00	2.49		
b	1.12	1.20	1.33		
b2 ⁽¹⁾	1.91	2.00	2.39		
b4 ⁽¹⁾	2.87	3.00	3.22		
С	0.55	0.60	0.69		
D (2)	20.80	20.95	21.10		
D1 ⁽³⁾	16.25	16.55	17.65		
D2	0.51	1.19	1.35		
E (2)	15.75	15.94	16.13		
E1 ⁽³⁾	13.46	14.02	14.16		
E2	4.32	4.91	5.49		
е		5.44 BSC.			
L	19.81	20.07	20.32		
L1 ⁽⁴⁾	4.10	4.19	4.40		
ØP ⁽⁵⁾	3.56	3.61	3.65		
ØP1	7.19 ref.				
Q	5.39	5.79	6.20		
S	6.04	6.17	6.30		
ECNI E24 0220 Pay A 12 May 200	24	•			

ECN: E24-0229-Rev. A, 13-May-2024

DWG: 6118

Notes

- Package reference: JEDEC TO-247, variation AD
- All dimensions are in mm
- Slot required, notch may be rounded
- (1) Dimension b2 and b4 does not include dambar protrusion
- (2) Dimension D and E do not include mold flash
- (3) Thermal pad contour optional within dimension D1 and E1
- (4) Lead Finish Uncontrolled In L1
- $^{(5)}$ ØP to have a draft angle of 1.5 $^{\circ}$ ref. to the top of the part with hole diameter of 3.91mm



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